

CLAIMS

1. Method for dispensing adhesive on a circuit-board carrier member for the securing thereto of a first component and a second component adjacent to and spaced apart from the first, wherein the adhesive is applied such that there are no discontinuities in a pattern of said adhesive within an anticipated footprint of the two components on the carrier member in an area of adjacency of the two components.
2. Method as claimed in Claim 1, wherein the discontinuities comprise any of starting-, end- and turning-point portions of the adhesive pattern.
3. Method as claimed in Claim 2, wherein the two components are to have respective bond-pads for the linking of the two components together in said area of adjacency by means of one or more electrical conductors, said linking constituting a transition from one component to the other, the adhesive being applied in said area of adjacency in substantially straight lines substantially transverse to a direction of said transition.
4. Method as claimed in Claim 3, wherein each of the substantially straight-lines of the adhesive pattern is of substantially constant width in a plane parallel to a major face of the carrier member over a portion of the substantially straight line which will lie within said footprint.

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5. Method as claimed in Claim 3, wherein each of the substantially straight-lines of the adhesive pattern is of substantially constant height above the carrier member over a portion of the substantially straight line which will lie within said footprint.
6. Method as claimed in Claim 1, wherein the adhesive is applied such that there are no discontinuities in the pattern of said adhesive within any part of said footprint.
7. Method as claimed in Claim 1, wherein the first and second components are each either a substrate or an electronic component.
8. Circuit-board comprising a carrier member, a first component and a second component adjacent to and spaced apart from the first, the two components being secured to the carrier member by means of an adhesive, wherein the adhesive is configured as a pattern on the carrier member and no discontinuities in the pattern are located within a footprint of the two components on the carrier member in an area of adjacency of the two components.
9. Circuit-board as claimed in Claim 8, wherein the discontinuities comprise any of starting-, end- and turning-point portions of the adhesive pattern.
10. Circuit-board as claimed in Claim 9, wherein the two components have respective bond-pads for the linking of the two components together in said area of adjacency by means of one or more electrical conductors, said linking constituting a transition from one

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component to the other, said adhesive being configured in said area of adjacency as substantially straight lines substantially transverse to a direction of said transition.

11. Circuit-board as claimed in Claim 8, wherein there are no discontinuities in the pattern of the adhesive within any part of said footprint.

12. Circuit-board as claimed in Claim 8, wherein the first and second components are each either a substrate or an electronic component.

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